# **MOSFET** - Power, Single N-Channel, TOLL

## **NTBLS1D5N08MC** 80 V, 1.53 mΩ, 298 A

#### Features

- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- Low Q<sub>G</sub> and Capacitance to Minimize Driver Losses
- Lowers Switching Noise/EMI
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### Applications

- Power Tools, Battery Operated Vacuums
- UAV/Drones, Material Handling
- BMS/Storage, Home Automation

#### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter		Symbol	Value	Unit		
Drain-to-Source Voltage		V <sub>DSS</sub>	80	V		
Gate-to-Source Voltage	Gate-to-Source Voltage		V <sub>GS</sub>	±20	V	
Continuous Drain Current $R_{\theta JC}$ (Note 2)	Steady	$T_C = 25^{\circ}C$	۱ <sub>D</sub>	298	A	
Power Dissipation $R_{\theta JC}$ (Note 2)	State	$T_C = 25^{\circ}C$	PD	250	W	
Continuous Drain Current $R_{\theta JA}$ (Notes 1, 2)	Steady State	$T_A = 25^{\circ}C$	Ι <sub>D</sub>	32	A	
Power Dissipation $R_{\theta JA}$ (Notes 1, 2)	51010	$T_A = 25^{\circ}C$	PD	2.9	W	
Pulsed Drain Current	$T_A = 25^{\circ}C, t_p = 10 \ \mu s$		I <sub>DM</sub>	4487	А	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	–55 to +150	°C		
Source Current (Body Diode)		IS	192	А		
Single Pulse Drain–to–Source Avalanche Energy ( $I_{L(pk)} = 31 \text{ A}, L = 3 \text{ mH}$ )		E <sub>AS</sub>	1441	mJ		
Lead Temperature Soldering Reflow for Solder- ing Purposes (1/8" from case for 10 s)		ΤL	260	°C		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State (Note 2)	$R_{\theta JC}$	0.5	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\thetaJA}$	43	

1. Surface-mounted on FR4 board using a 1 in<sup>2</sup> pad size, 1 oz. Cu pad.

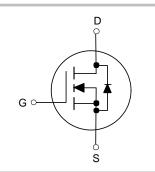
The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.



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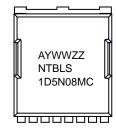
V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
80 V	1.53 mΩ @ 10 V	298 A
80 V	3.7 mΩ @ 6 V	290 A





CASE 100CU

#### MARKING DIAGRAM



NTBLS1D5N08MC = Specific Device Code

- A = Assembly Location
- Y = Year
- WW = Work Week ZZ = Lot Traceability

#### ORDERING INFORMATION

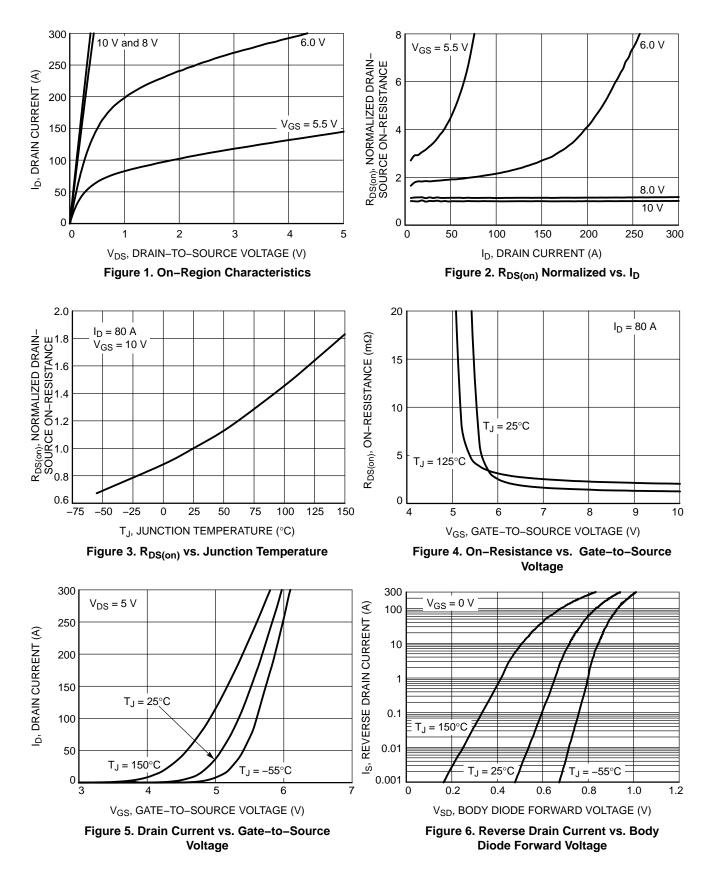
See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

#### Table 1. ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = $25^{\circ}$ C unless otherwise noted)

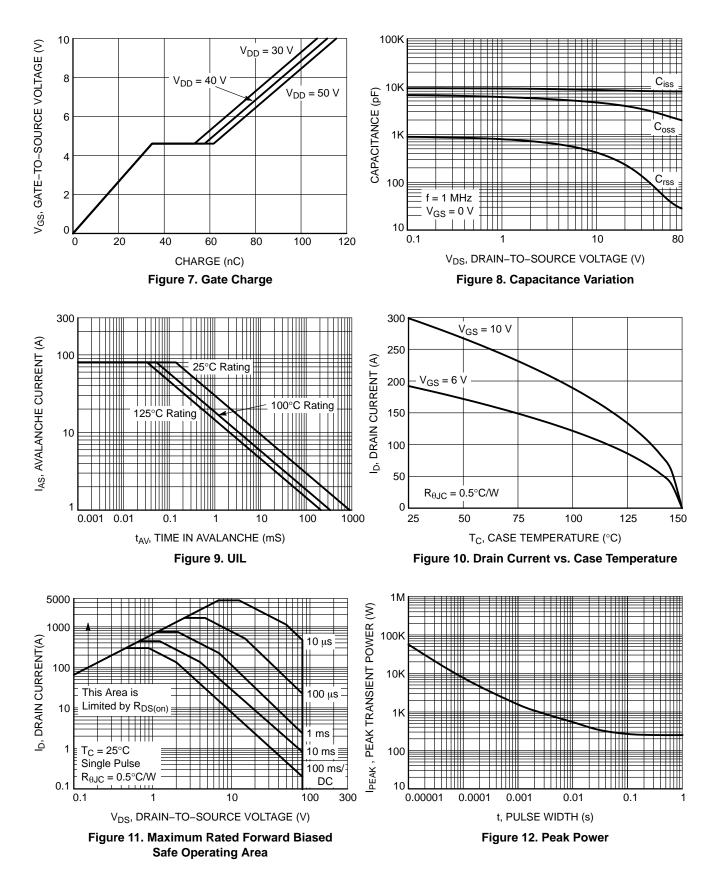
Parameter	Symbol	Test Conditions		Min	Тур	Max	Units
OFF CHARACTERISTICS				-			
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$I_D = 250 \ \mu A, \ V_{GS} = 0 \ V$		80	_	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>	$I_D = 250 \ \mu\text{A}$ , ref to $25^{\circ}\text{C}$		-	78	-	mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 80 V, V <sub>GS</sub> = 0 V	T <sub>J</sub> = 25°C T <sub>J</sub> = 125°C	-	-	1 100	μΑ μΑ
Gate-to-Source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>G</sub>	<sub>S</sub> = ±20 V	-	_	±100	nA
ON CHARACTERISTICS (Note 3)			-		1		1
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 710 μA		2.0	3.0	4.0	V
Negative Threshold Temperature Coefficient	V <sub>GS(th)</sub> /T <sub>J</sub>	$I_{\rm D} = 710 \mu\text{A}, \text{ ref to } 25^{\circ}\text{C}$		-	-8.3	-	mV/°C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 80 \text{ A}$		-	1.30	1.53	mΩ
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	$V_{GS} = 6 \text{ V}, \text{ I}_{D} = 63 \text{ A}$		-	2.0	3.7	mΩ
Forward Transconductance	9 <sub>FS</sub>	$V_{DS} = 5 \text{ V}, \text{ I}_{D} = 80 \text{ A}$		-	220	-	S
Gate-Resistance	R <sub>G</sub>	$T_A = 25^{\circ}C$		-	0.7	-	Ω
CHARGES & CAPACTIANCES							
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 40 V, f = 1 MHz		-	8170	-	pF
Output Capacitance	C <sub>oss</sub>			-	3025	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>			_	82	-	pF
Total Gate Charge	Q <sub>G(tot)</sub>	$V_{GS} = 10 \text{ V}, \text{ V}_{DS} = 40 \text{ V},$ $I_D = 80 \text{ A}$		-	111	-	nC
Threshold Gate Charge	Q <sub>G(th)</sub>			-	22	-	
Gate-to-Source Charge	Q <sub>gs</sub>			-	35	-	
Gate-to-Drain Charge	Q <sub>gd</sub>			-	23	-	
Output Charge	Q <sub>oss</sub>			-	166	-	
Sync Charge	Q <sub>sync</sub>			-	94	-	
Plateau Voltage	V <sub>P</sub>			-	5	-	V
SWITCHING CHARACTERISTICS, $V_{GS} = 10$	<b>) V</b> (Note 3)						
Turn–On Delay Time	t <sub>d(on)</sub>	$V_{GS} = 10 \text{ V}, \text{ V}_{DS} = 40 \text{ V},$ $I_D = 80 \text{ A}, \text{ R}_G = 6 \Omega$		-	38	-	ns
Rise Time	t <sub>r</sub>			-	34	-	ns
Turn–Off Delay Time	t <sub>d(off)</sub>			-	74	-	ns
Fall Time	t <sub>f</sub>			-	37	-	ns
DRAIN-SOURCE DIODE CHARACTERIST	cs						
Forward Diode Voltage	V <sub>SD</sub>	$I_{S} = 80 \text{ A}, V_{GS} = 0 \text{ V}$	$T_J = 25^{\circ}C$	-	0.8	1.3	V
		$I_{S} = 80 \text{ A}, V_{GS} = 0 \text{ V}$	$T_J = 125^{\circ}C$	-	0.7	-	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 40 A, di/dt = 300 A/μs		-	19	-	nS
Reverse Recovery Charge	Q <sub>rr</sub>	1		-	42	-	nC
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 40 A, di/dt = 1000 A/μs		-	17	-	nS
Reverse Recovery Charge	Q <sub>rr</sub>			-	121	-	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.3. Switching characteristics are independent of operating junction temperatures

#### **TYPICAL CHARACTERISTICS**



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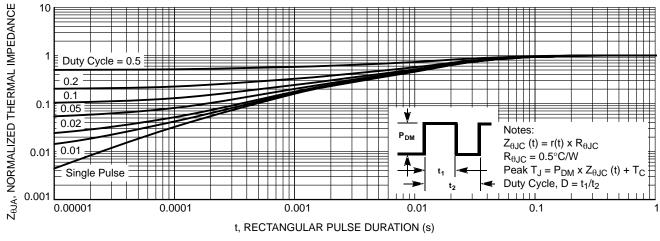


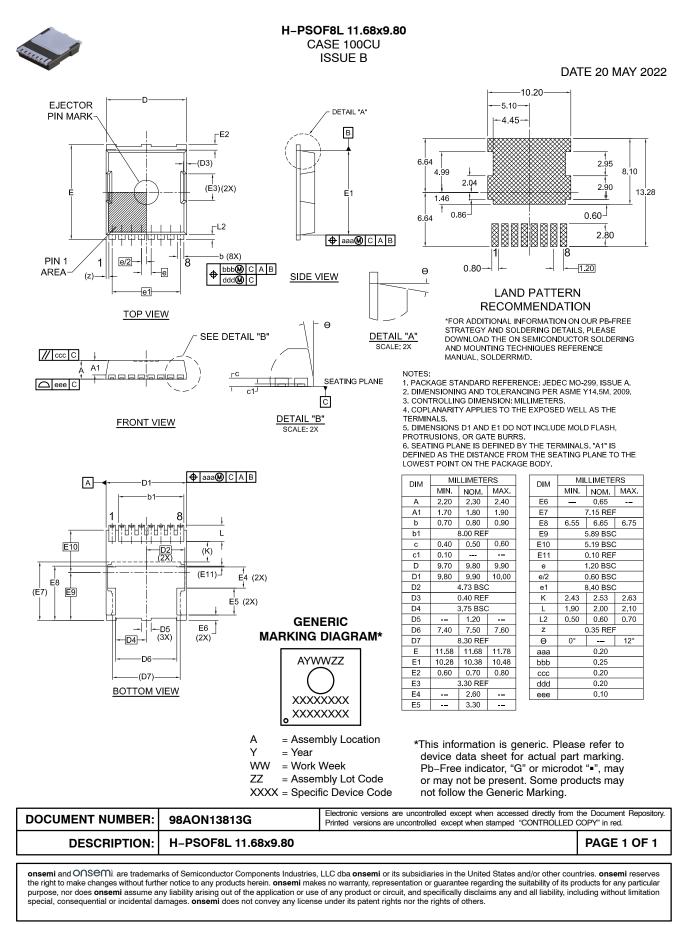
Figure 13. Transient Thermal Impedance

#### **DEVICE ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>
NTBLS1D5N08MC	NTBLS 1D5N08MC	M0–299A (Pb–Free)	2000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# ONSEM<sup>1</sup>.



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